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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/020,594	12/13/2001	Jurgen Schredl	70408	7149
23872 75	90 03/29/2005		EXAM	INER
MCGLEW & TUTTLE, PC			TRAN, LEN	
	UGH STATION PLAZA GH, NY 10510-0827		ART UNIT	PAPER NUMBER
•			1725	

DATE MAILED: 03/29/2005

Please find below and/or attached an Office communication concerning this application or proceeding.

Attachment(s)      Notice of References Cited (PTO-892)   Notice of Draftsperson's Patent Drawing Resolution Disclosure Statement(s) (PTO-Paper No(s)/Mail Date	eview (PTO-948) P 1449 or PTO/SB/08) 5) 🔲 N	nterview Summary (PTO-413) aper No(s)/Mail Date lotice of Informal Patent Application (PTO-152) tther:

### **DETAILED ACTION**

#### Continued Examination Under 37 CFR 1.114

1a. A request for continued examination under 37 CFR 1.114, including the fee set forth in 37 CFR 1.17(e), was filed in this application after final rejection. Since this application is eligible for continued examination under 37 CFR 1.114, and the fee set forth in 37 CFR 1.17(e) has been timely paid, the finality of the previous Office action has been withdrawn pursuant to 37 CFR 1.114. Applicant's submission filed on 12/2/04 has been entered.

### Claim Rejections - 35 USC § 103

- 1. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:
  - (a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.
- 2. This application currently names joint inventors. In considering patentability of the claims under 35 U.S.C. 103(a), the examiner presumes that the subject matter of the various claims was commonly owned at the time any inventions covered therein were made absent any evidence to the contrary. Applicant is advised of the obligation under 37 CFR 1.56 to point out the inventor and invention dates of each claim that was not commonly owned at the time a later invention was made in order for the examiner to consider the applicability of 35 U.S.C. 103(c) and potential 35 U.S.C. 102(e), (f) or (g) prior art under 35 U.S.C. 103(a).

3. Claims 1-9, 12-15, and 17-20 are rejected under 35 U.S.C. 103(a) as being unpatentable over Leicht et al(US 5,551,627), and further in view of Gotman (US 4,404,453).

Leitcht et al disclose the process for producing a contact structure for connecting two substrates comprising the steps of applying solder material to terminal to form spacing metallizations, and bonding the first substrate to the second substrate, wherein the solder is a spherical shape (figure 3, col. 4, lines 5-9). An adhesive compound is applied to the solder (col. 4, lines 40-51).

Leicht et al fail to disclose partially fusing the solder with a laser energy.

However, Gotman discloses using laser energy to partially melt the solder (col. 3, lines 19-22) for the purpose of avoiding or minimizing any damage to the parts being attached together (col. 2, lines 35-40). In addition, Gotman discloses heating the solder (72) to become partially liquefied and then fusion takes place, in which during the bonding action (col. 4, lines 18-36).

Therefore, it would have been obvious to one of ordinary skill in the art at the time applicant's invention was made to provide a laser heating means to partially melt the solder as taught by Gotman, in Leicht et al in order to prevent any damage to the parts.

4. Claims 10, 11, and 16 are rejected under 35 U.S.C. 103(a) as being unpatentable over Leicht et al (US 5,551,627), and further in view of Beddingfield et al (US 5,710,071).

Leicht et al disclose the claimed invention above in paragraph 3, but fail to teach filling the gap between the substrates with a filler material.

However, Beddingfield et al disclose applying a filler (encapsulant) material in the gap of the substrates for the purpose of expelling any trap air and to prevent the chip from warping (abstract).

Therefore, it would have been obvious to one of ordinary skill in the art at the time applicant's invention was made to have filler material in between the substrates as taught by Beddingfield et al, in Leicht et al in order to expel air and prevent warping.

#### Response to Arguments

Applicant's arguments filed on July 01, 2004 have been fully considered but they are not 5. persuasive.

Applicant argues that Gotmann fails to teach partially melting the solder during the bonding action. However, examiner respectfully disagrees, since in column 4, lines 18-36, Gotmann discloses partially melting the solder and then fusion takes place. Therefore, the solder is partially melted during the bonding action.

Applicant argues that the applied prior arts fail to teach a partial fusion of the spacing metallization. However, examiner respectfully disagrees, since the claimed language with the broadest interpretation is not defined over the prior arts of record. .

## Inquiry

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Len Tran whose telephone number is (571) 272-1184. The examiner can normally be reached on M-F, 8:30 - 5.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Tom Dunn can be reached on (571) 272-1171. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

Len Tran Examiner

Art Unit 1725

March 24, 2005